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In the Specification:

Please replace paragraph 0015 beginning at page 6 with the following amended paragraph:

- In accordance with an aspect of this invention, improved rheology, and in particular reduced viscosity of the polymer overmolding material when it is flowing around features of the circuit board 12, semi-conductor chips 14, 16 and connections 18 is achieved by utilizing an overmolding composition comprising a synthetic resin matrix and inorganic filler particles substantially uniformly distributed in the matrix, wherein the particles have a platelet structure.

As used herein, the expression "platelet structure" refers to a particle structure defined by opposite substantially flat and substantially parallel faces, the distance between the faces defining a thickness of the particles. The expression "substantially flat and substantially parallel faces" means that the thickness of the particle varies very little, typically less than the average thickness of the particle, and any deviation from flat and parallel, is minor, typically less than the average thickness of the particle. Desirably, the weight average ratio of surface area of a face of ~~each~~ a particle to the thickness of ~~each~~ the particle is at least 100, and preferably from about 200 to about 1000. The weight average ratio of surface area of a face of ~~each~~ a particle to the thickness of ~~each~~ the particle is determined by taking the sum of the products of the weight of ~~each~~ particles having a particle times the particular ratio of surface area to thickness for that particle, and dividing the sum by the total weight of all particles. Desirably, the particles have a thickness on the order of one nanometer (10^{-9} meter), but may range from about one nanometer to several nanometers (e.g., 20 nm).- -